

Bringing tomorrow's electronics to life



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mrsi.mycronic.com



North America

MRSI Systems

554 Clark Rd.,
Tewksbury, MA
USA 01876
Tel: +1 978 667 9449
sales.mrsi@mycronic.com
mrsi.mycronic.com

Asia

MRSI Automation (Shenzhen) Co., Ltd

101, Block A, Huahan
Innovation Park,
Langshan Road, Shenzhen,
China 518057
Tel: +86 755 26414155

EMEA

Distributor and Demo Center Distek Strumenti & Misure Srl

Via Guglielmo Marconi, 15,
80125 Napoli NA, Italy
Tel: +39 348 3837815
marco@distek.it

MRSI Systems (Mycronic Group), is the leading manufacturer of fully automated, high-speed, high-precision and flexible eutectic and epoxy die bonding systems. We offer solutions for research and development, low-to-medium volume production, and high-volume manufacturing of photonic devices such as lasers, detectors, modulators, AOCs, WDM/EML TO-Cans, Optical transceivers, LiDAR, VR/AR, sensors, and optical imaging products. With 40+ years of industry experience and our worldwide local technical support team, we provide the most effective systems and assembly solutions for all packaging levels including chip-on-wafer (Cow), chip-on-carrier (CoC), PCB, and gold-box packaging. For more information visit www.mrsisystems.com.

Mycronic is a Swedish high-tech company engaged in the development, manufacture and marketing of production equipment with high precision and flexibility requirements for the electronics industry. Mycronic headquarters is located in Täby, north of Stockholm and the Group has subsidiaries in China, France, Germany, Japan, Singapore, South Korea, the Netherlands, United Kingdom and the United States. Mycronic (MYCR) is listed at Nasdaq Stockholm. www.mycronic.com

Specifications are subject to change without notice.

202510_MRSI-175Agv3

MRSI-175Ag **EPOXY DISPENSER**



*Available on the MRSI 175Ag+

The background of the slide is a photograph of several communication towers situated on a densely forested hill. The scene is captured during sunset or sunrise, with a warm, orange glow on the horizon and a sky filled with dark, dramatic clouds. The towers are silhouetted against the bright sky. A large, semi-circular blue graphic element is positioned on the left side of the slide, containing the text.

MRSI Systems has been serving optoelectronic and microelectronic customers for over 40 years and understands their requirement to scale efficiently in today's fast-paced marketplace.

Applications exist across a wide range of market segments, such as life & health sciences, aerospace, defense, automotive, lighting, communications, and more.

MRSI's die bonding solutions help our customers to enable just-in-time supply and fast-paced innovations of critical components for high-growth market segments. The MRSI-175Ag Conductive Epoxy Dispenser handles the most demanding dispensing applications such as semiconductor packaging, microwave & RF modules, multi-chip modules, optical modules, hybrid circuits, sensors, and MEMS.

Our die bonding solutions are built on standardized hardware and software platforms configured to minimize process deviations, reduce NPI cost, deliver long term proven product reliability and supported by our global customer service team. These factors deliver the best financial returns in the industry.



MRSI-175Ag Epoxy Dispenser Highly Configurable



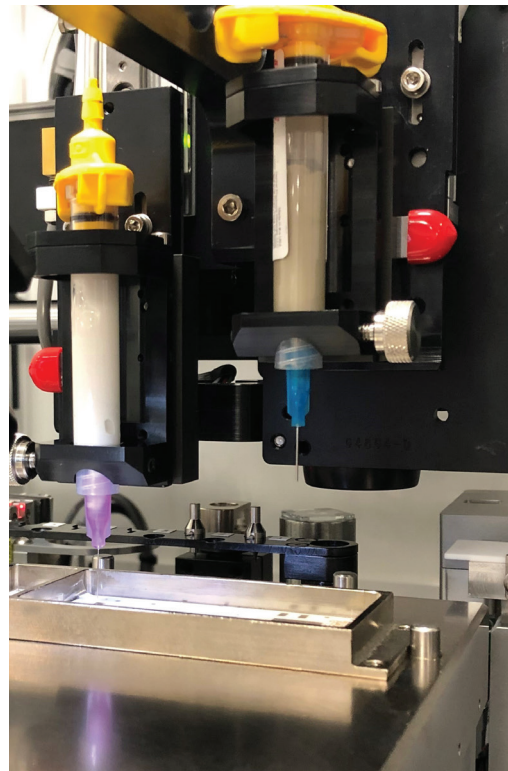
Assembly Technologies

- Underfill
- Epoxy die attach
- Encapsulation
- Multi-pin stamping
- UV epoxy



Flexible Dispensing Platform

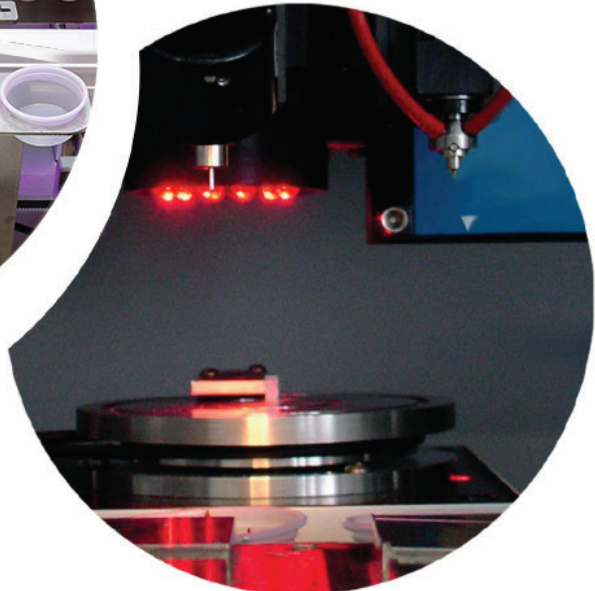
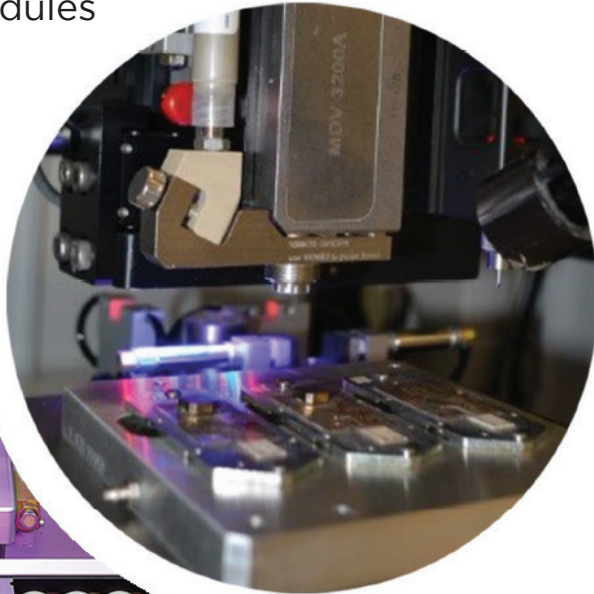
- Increased capacity at lower cost
- Lower cost of ownership
- Less labor cost
- Higher yields
- Flexibility
- Ultra-high speed
- 35% more energy efficient
- 25µm accuracy (10µm accuracy MRSI-175Ag+ available)





Applications

- Semiconductor packaging
- Microwave & RF modules
- Multi-chip modules
- Optical modules
- Hybrid circuits
- Sensors
- MEMS



Options

- Laser height sensor
- Confocal height sensor
- Conveyor
- Jet
- Stamping
- Real-time video monitoring